

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination DANZIGER ET AL.	
		Examiner Evan Pert	Art Unit 2829	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-5,886,414	03-1999	Galloway, Terry R.	257/784
	B	US-5,623,394	04-1997	Sherif et al.	361/705
	C	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Shaukatullah et al., "Thermal Enhancement of Flip-Chip Packages with Radial-Finger-Contact Spring", May 1995, IEEE 45 th Electronic Components and Technology Conference, pages 865-871.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.